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INCLUSION OF THE PROPERTY OF T

- 1. A chemical-mechanical polishing composition comprising:
 - (a) fumed silica particles,
 - (b) about 5×10^{-3} to about 10 mmoles/kg of at least one alkaline earth metal selected from the group consisting of calcium, strontium, barium, and mixtures thereof, based on the total weight of the polishing composition,
 - (c) about 0.1 to about 15 wt.% of an oxidizing agent, and
 - (d) a liquid carrier comprising water,

wherein the polishing composition has a pH of about 7 to about 13.

- 2. The polishing composition of claim 1, wherein the polishing composition has a pH of about 8 to about 11.
- 3. The polishing composition of claim 2, wherein the furned silica particles are present in the polishing composition in an amount of about 1 to about 10 wt.% based on the total weight of the polishing composition.
- 4. The polishing composition of claim 3, wherein the oxidizing agent is an inorganic or organic per-compound.
- 5. The polishing composition of claim 4, wherein the oxidizing agent is present the draw of in the polishing composition in an amount of about 0.5 to about 8 wt.% based on the total to be required weight of the polishing composition.
- 6. The polishing composition of claim 5, wherein the oxidizing agent is present allowed and figure in the polishing composition in an amount of about 1 to about 5 wt.% based on the total assertion as a result of the polishing composition.
- 7. The polishing composition of claim 4, wherein the polishing composition further comprises an inorganic acid selected from the group consisting of nitric acid, phosphoric acid, sulfuric acid, salts thereof, and combinations thereof.
- 8. The polishing composition of claim 4, wherein the polishing composition further comprises an organic acid selected from the group consisting of oxalic acid, malic acid, malonic acid, tartaric acid, acetic acid, lactic acid, propionic acid, phthalic acid, benzoic acid, citric acid, succinic acid, salts thereof, and combinations thereof.